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APPLICATION NO.	FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09 918,183	918,183 07-30-2001		Daniel B. D'Souza	00-464	2696
24319	7590	07-30-2003			
LSI LOGIC		RATION	EXAMINER		
1621 BARBER LANE MS: D-106 LEGAL				PATEL, PARESH H	
MILPITAS, CA 95035				ART UNIT	PAPER NUMBER
				2829	

DATE MAILED: 07/30/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)					
	•	09/918,183	D'SOUZA, DANIEL B.					
•	Office Action Summary	Examiner	Art Unit					
		Paresh Patel	2829					
Period fo	The MAILING DATE of this communication or Reply	appears on the cover sheet v	vith the correspondence address					
THE - Exte after - If the - If NC - Failu - Any (ORTENED STATUTORY PERIOD FOR REMAILING DATE OF THIS COMMUNICATIOnsions of time may be available under the provisions of 37 CFI SIX (6) MONTHS from the mailing date of this communication period for reply specified above is less than thirty (30) days, a period for reply is specified above, the maximum statutory per to reply within the set or extended period for reply will, by streply received by the Office later than three months after the mad patent term adjustment. See 37 CFR 1.704(b).	N. R 1.136(a). In no event, however, may a to reply within the statutory minimum of the riod will apply and will expire SIX (6) MC adute, cause the application to become A	reply be timely filed irty (30) days will be considered timely. NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).					
1)⊠	Responsive to communication(s) filed on	05/20/2003.						
2a)⊠		This action is non-final.						
3) 🗌	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.							
· _	ion of Claims	dia.						
•	Claim(s) 1-20 is/are pending in the application.							
	4a) Of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim(s) 10-20 is/are without the state of the above claim (s) 10-20 is/are without the state of the above claim (s) 10-20 is/are without the state of the above claim (s) 10-20 is/are without the above claim (s) 10-20 is/	drawn from consideration.						
·	Claim(s) is/are allowed.							
	Claim(s) <u>1-9</u> is/are rejected.							
•	Claim(s) is/are objected to.							
	Claim(s) are subject to restriction ar ion Papers	nd/or election requirement.						
9) 🗌	The specification is objected to by the Exan	niner.						
10)	The drawing(s) filed on is/are: a) \square a	ccepted or b) objected to by	the Examiner.					
	Applicant may not request that any objection t							
11)	The proposed drawing correction filed on $_$		disapproved by the Examiner.					
	If approved, corrected drawings are required i							
12)	The oath or declaration is objected to by the	e Examiner.						
Priority (under 35 U.S.C. §§ 119 and 120							
13)	Acknowledgment is made of a claim for for	reign priority under 35 U.S.C	. § 119(a)-(d) or (f).					
a)	☐ All b)☐ Some * c)☐ None of:							
	1. Certified copies of the priority docum	nents have been received.						
	2. Certified copies of the priority docum	nents have been received in	Application No					
* (3. Copies of the certified copies of the application from the Internationa See the attached detailed Office action for a	l Bureau (PCT Rule 17.2(a))						
14) 🗌 A	Acknowledgment is made of a claim for dom	estic priority under 35 U.S.C	. § 119(e) (to a provisional application).					
) The translation of the foreign language Acknowledgment is made of a claim for don							
Attachmen								
2) Notic	te of References Cited (PTO-892) te of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449) Paper No) 5) Notice o	v Summary (PTO-413) Paper No(s) f Informal Patent Application (PTO-152)					
S Patent and T	rademark Office							

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DETAILED ACTION

Response to Arguments

Applicant's arguments filed 05/20/2003 have been fully considered but they are not persuasive.

In combination DeHaven et al. and D'Souza et al. discloses all the elements of claimed invention including applicant's argument where applicant argues that neither one of the cited references discloses or suggests providing a plurality of DRAM dies on the wafer and conductive connection (inherent to testing because conductive connection is needed to test the ICs of product wafer) providing that said DRAM's <u>can</u> <u>be</u> burned-in on the wafer.

Applicant argues that there is no suggestion to combine the references, the examiner recognizes that obviousness can only be established by combining or modifying the teachings of the prior art to produce the claimed invention where there is some teaching, suggestion, or motivation to do so found either in the references themselves or in the knowledge generally available to one of ordinary skill in the art.

See *In re Fine*, 837 F.2d 1071, 5 USPQ2d 1596 (Fed. Cir. 1988) and *In re Jones*, 958 F.2d 347, 21 USPQ2d 1941 (Fed. Cir. 1992). In this case, DeHaven suggests testing of product (ICs on wafer) wafer with testing wafer (CDW). CDW also performs burn-in operations on the ICs of product wafer. At lines 65-67 of column 4 and at lines1-7 of column 5, DeHaven discloses **ICs of the product wafer are one or more of** microprocessors, microcontrollers, digital signal processors, analog filters, A/D or D/A

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converters, memory circuits, EEPROMs, EPROMs, DRAMs, SRAMs ... or any other compatible IC device.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-9 are rejected under 35 U.S.C. 103(a) as being unpatentable over D'Souza et al. (US 5396170) in view of DeHaven et al. (US 6411116).

Regarding claim 1, D'Souza et al. (hereinafter D'Souza) in fig. 9 discloses: a plurality of DRAM dies [908a-908d], wherein each DRAM die has a test data in pad [contact terminal of TDI at 908a] and a test data out pad [contact terminal of TDO at 908a]; and

conductive connections [electrical connection between TDO of 908a and TDI of 908b] interconnecting the test data out and test data in pads of the DRAM dies.

D'Souza does not disclose a plurality of DRAM dies on the wafer and conductive connection providing that said **DRAM's can be burned-in on the wafer**. Rather, D'Souza discloses DRAM dies are mounted on a printed circuit board [902] of probe card [900]. Here the DRAM dies are used to conduct test on DUT [952 of fig. 10].

DeHaven et al. (hereinafter DeHaven) in fig. 3-5 discloses a plurality of DRAM dies [34 and see lines 53-59 of column 3] on the wafer [16] and said conductive

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connection providing that said **DRAM's can be burned-in on the wafer** [lines 35-44 of column 3]. It would have been obvious to a person having ordinary skill in the art at the time the invention to use connection of **DRAM** dies of D'Souza with the wafer as taught by DeHaven, in order to study reliability and functionality of individual dies on a wafer before singulating and shipping, because individual testing of **DUT** (packaged chip or die) is costly if failure rate is higher during manufacturing process (also see lines 44-67 of column 2).

Regarding claim 2, D'Souza discloses: DRAM dies are IEEE1149.1 compliant [lines 49-52 of column 13], and include Test Data In (TDI), Test Data Out (TDO), Test Clock (TCK), and Test Mode Set (TMS) pads [see fig. 9].

Regarding claim 3, D'Souza discloses: TDO pad of each DRAM die is connected to the TDI pad of next DRAM die [see fig. 9].

Regarding claims 4-5, D'Souza discloses: TMS and TCK pads of the DRAM dies are connected in parallel [see fig. 9] via metal lines [conductive lines connecting TMS and TCK to 908a-d] running along a scribe area [area of 900].

Regarding claim 6, D'Souza discloses the DRAM dies are arranged in rows [see fig. 9], and each DRAM die in a given row is daisy chained to the next DRAM die in the raw [fig. 9].

Regarding claims 7-8, D'Souza discloses metal line to connect two DRAM dies [conductive lines connecting TDO and TDI to 908a-d]. DeHaven and D'Souza discloses claimed invention except for last DRAM die in raw is daisy chained to the first DRAM die in the next raw. It would have been an obvious matter of design choice to

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connect last DRAM die in raw is daisy chained to the first DRAM die in the next raw, since applicant has not disclosed that last DRAM die in raw is daisy chained to the first DRAM die in the next raw solves any stated problem or is for any particular purpose and it appears that the invention would perform equally well with combination of DeHaven and D'Souza.

Regarding claims 9, DeHaven discloses the DRAM dies on the wafer are connected to the power busses [26-28 of column 9].

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Paresh Patel whose telephone number is 703-306-5859. The examiner can normally be reached on M-F (8:30 to 4:30).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 703-308-1233. The fax phone numbers for the organization where this application or proceeding is assigned are 703-872-9318 for regular communications and 703-872-9319 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

Paresh Patel July 24, 2003

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